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(54) Title: PROCESSOR ASSEMBLY, QUANTUM COMPUTING ARRANGEMENT AND METHOD

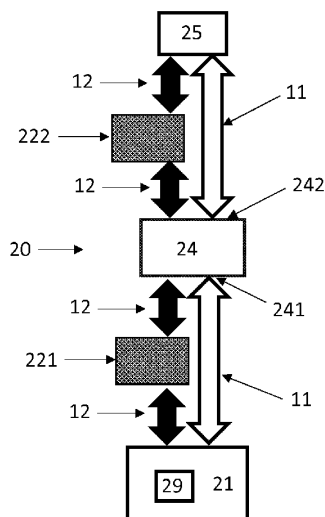


Fig. 2a

(57) Abstract: A processor assembly for a quantum computer comprising a carrier and at least one quantum processor die mounted on the carrier and a first thermal anchor point which is in thermal contact with the carrier. The assembly also comprises a first electrical connector and an electrical signal connection with a first end which is electrically connected to the carrier and a second end which is electrically connected to the first electrical connector. The processor assembly also comprises a second thermal anchor point. The second thermal anchor point is thermally separated from the first thermal anchor point and the second thermal anchor point is in thermal contact with the first electrical connector.

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